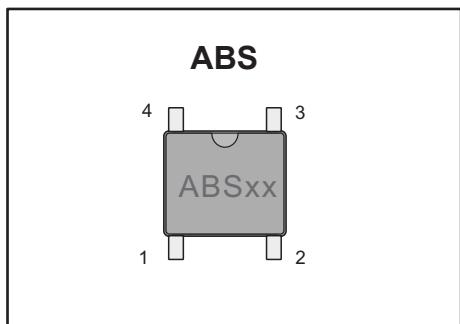


## SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS

### PINNING

PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )



### Features

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
- ◆ Small size, simple installation
- ◆ High surge current capability
- ◆ Glass passivated chip junction

### Mechanical Data

- ◆ **Case** : JEDEC ABS Molded plastic body
- ◆ **Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity** : Polarity symbol marking on body
- ◆ **Mounting Position** : Any
- ◆ **Weight** : 0.003 ounce, 0.098 grams

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

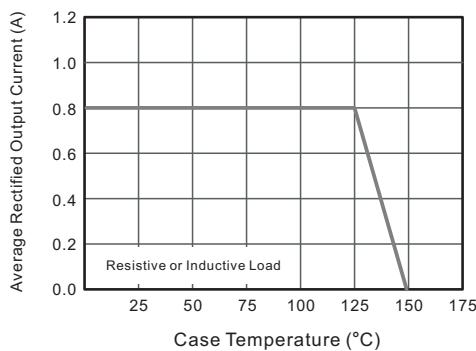
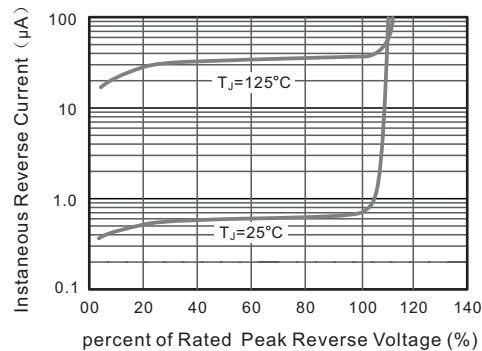
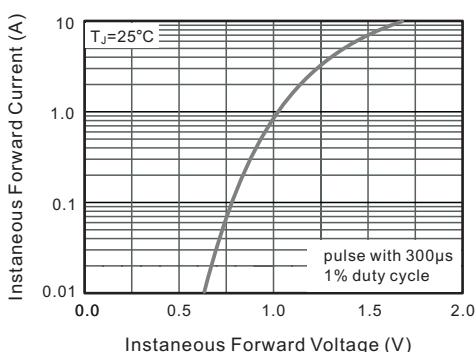
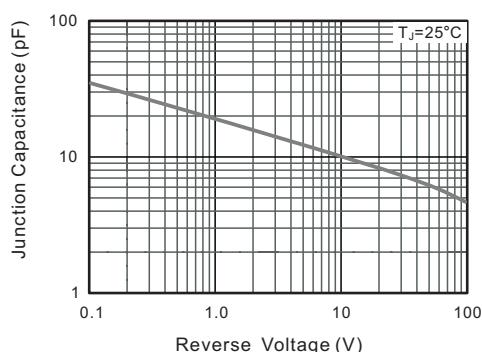
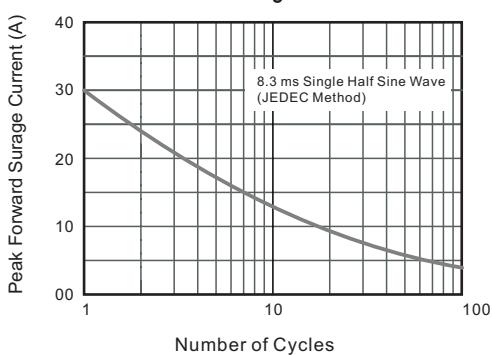
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ABS2	ABS4	ABS6	ABS8	ABS10	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	200	400	600	800	1000	V
Maximum average forward rectified current at $T_C=125^\circ C$	$I_{F(AV)}$			0.8			A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$			30			A
Maximum instantaneous forward voltage drop per leg at 0.8A	$V_F$			1.1			V
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=100^\circ C$	$I_R$			5 100			$\mu A$ $\mu A$
Typical thermal resistance	$R_{\theta JL}$ $R_{\theta JA}$			25 80			$^\circ C/W$
Operating temperature range	$T_J$		-55 to +150				$^\circ C$
storage temperature range	$T_{STG}$		-55 to +150				$^\circ C$

NOTES: 1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads

2. On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad

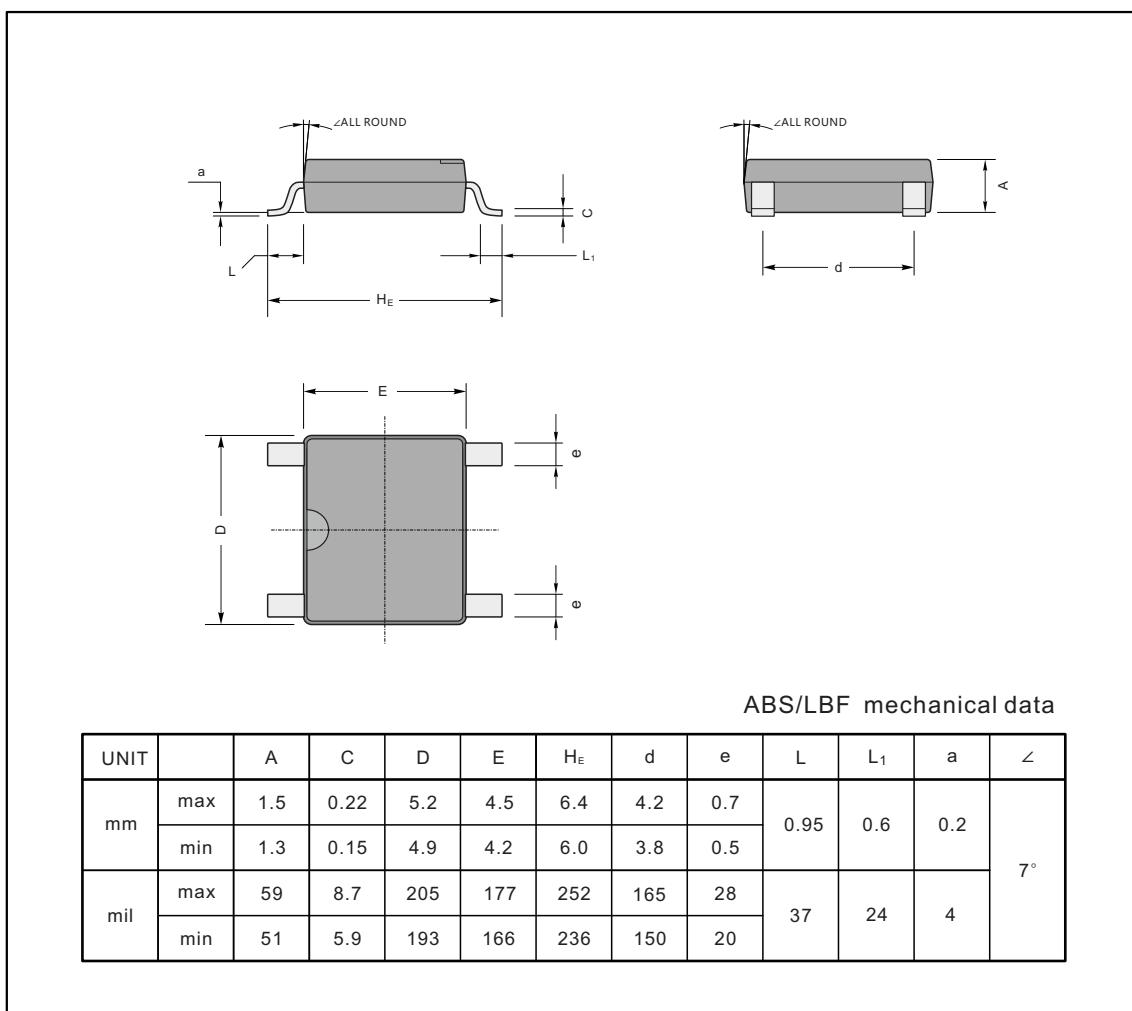
3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

**Fig.1 Average Rectified Output Current Derating Curve**

**Fig.2 Typical Reverse Characteristics**

**Fig.3 Typical Instantaneous Forward Characteristics**

**Fig.4 Typical Junction Capacitance**

**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**


## PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

**ABS**



### The recommended mounting pad size

